

# **Multiannual work programme 2023-2027**

Version 9.0

# **VERSION HISTORY:**

V9.0 approved on December 20, 2024

- Change of terminology to Electronic Components and Systems calls and Chips for Europe Initiative calls.
- Updated information in the core text of the work programme
- Introduced descriptions of calls to be launched in 2025 (Appendices 5 and 6)

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# 1. INTRODUCTION

The Multi-annual Work Programme 2023-2027 (WP2023-2027) of the Chips Joint Undertaking (Chips JU)<sup>1</sup>, covers the activities of the Chips JU from 1 January 2023 to 31 December 2027.

The scope of the WP2023-2027 is to inform in a transparent manner about the Joint Undertaking's future activities in particular its intentions to support and fund actions in specific fields of research and innovation, in accordance with the legal provisions, in particular:

- Council Regulation (EU) 2021/2085 of 19 November 2021 establishing the KDT Joint Undertakings referred to as Single Basic Act (SBA), amended by Council Regulation (EU) 2023/1782 of 25 July 2023, referred to as Chips Regulation,
- Regulation (EU, Euratom) 2018/1046 of the European Parliament and of the Council of 18 July 2018 on the **financial rules** applicable to the general budget of the Union,
- Regulation 2021/695 of the European Parliament and of the Council of 28 April 2021 establishing **Horizon Europe** (**HE**) the Framework Programme for Research and Innovation, laying down its rules for participation and dissemination;
- Regulation (EU) 2021/694 of the European Parliament and of the Council of 29 April 2021 establishing the **Digital Europe Programme** (DEP).
- Commission Delegated Regulation (EU) 2019/887 of 13 March 2019 on the model financial regulation for public-private partnership bodies referred to in Article 71 of Regulation (EU, Euratom) 2018/1046 of the European Parliament and of the Council;
- Financial rules of the Chips Joint Undertaking, decision KDT GB 2021.02, Annex 12;
- The **Strategic Research and Innovation Agenda** (SRIA) 2023 issued by the Private Members Board (decision KDT GB 2023.34).

# 1.1 Objectives of the Chips JU

The joint undertakings have three general objectives, in accordance with Article 4 of the SBA:

- strengthening and integrating the scientific, innovation and technological capacities and facilitating collaborative links,
- securing sustainability-driven global leadership and resilience of Union value chains in key technologies and industries and on developing, and
- accelerating the uptake of innovative solutions throughout the Union addressing climate, environmental, health, digital and other global challenges.

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<sup>&</sup>lt;sup>1</sup> Council Regulation (EU) 2023/1782 of 25 July 2023

The SBA also lists five specific objectives for the Joint Undertakings:

- enhance the critical mass and scientific and technological capabilities and competences,
- accelerate the green and digital transitions,
- enhance the research and innovation capabilities and performance of existing and new European innovation ecosystem and economic value chains, including in start-ups and small and medium-sized enterprises (SME),
- accelerate the deployment, uptake and diffusion of innovative solutions, technologies, services and skills, and
- deliver environmental, energy, resource-saving, societal, circularity and productivity improvements in new products, technologies, applications and services by exploiting Union capabilities and resources.

In addition to the objectives set out above, the Chips JU has the following general objectives (SBA, Article 126):

- 1. reinforce the Union's strategic autonomy in electronic components and systems to support future needs of vertical industries and the economy at large. The overall target is to contribute towards doubling the value of the design and production of electronic components and systems in Europe by 2030, in line with the weight of the Union in products and services;
- 2. establish Union scientific excellence and innovation leadership in emerging components and systems technologies, including in activities related to lower TRLs; and promote the active involvement of SMEs, which, for all research and innovation activities, including those related to the Chips for Europe Initiative established by Regulation (EU) 2023/1781, shall represent at least one third of the total number of participants in indirect actions and at least 20 % of public funding should go to them
- 3. ensure that components and systems technologies address Europe's societal and environmental challenges. The target is to align with the Union policy on energy efficiency and contribute towards the reduction of energy consumption by 32.5 % in 2030.
- 4. achieve large-scale technological capacity building and support related research and innovation activities throughout the Union's semiconductor value chain to enable development and deployment of cutting- edge semiconductor technologies, next-generation semiconductor technologies and cutting-edge quantum technologies and the innovation of established technologies that will reinforce advanced design, systems integration and chip production capabilities in the Union, thereby increasing the competitiveness of the Union; and contribute to the achievement of the green and digital transitions, in particular by reducing the climate impact of electronic systems, improving the sustainability of next- generation Chips and strengthening the circular economy processes, contribute to quality jobs within the semiconductor ecosystem and address security-by-design principles, which provide protection against cybersecurity threats.

Next to those general objectives, the Chips JU also has the following specific objectives:

1. support research and development for establishing design and production capabilities in Europe for strategic application areas;

- 2. launch a balanced portfolio of large and small projects supporting the fast transfer of technologies from the research to the industrial environment;
- 3. foster a dynamic Union-wide ecosystem based on digital value-chains with simplified access to newcomers;
- 4. support research and development for enhancing component technologies that guarantee security, trust and energy-efficiency for critical infrastructures and sectors in Europe;
- 5. foster mobilisation of national resources and ensure coordination of Union and national research and innovation programmes in the field of electronic components and systems;
- 6. establish coherence between the Strategic Research and Innovation Agenda of the Key Digital Technologies Joint Undertaking and Union policies so that electronics components and systems technologies contribute efficiently.
- 7. build up advanced design capacities for integrated semiconductor technologies;
- 8. enhance existing and develop new advanced pilot lines across the Union to enable development and deployment of cutting-edge semiconductor technologies and next-generation semiconductor technologies;
- 9. build advanced technology and engineering capacities for accelerating the innovative development of cutting- edge quantum Chips and associated semiconductor technologies;
- 10. establish a network of competence centres across the Union by enhancing existing or creating new facilities.

Besides those objectives, the Chips JU also contributes to a larger effort envisioned in the following documents:

- Joint Declaration on Processor and Semiconductor Technologies<sup>2</sup> (7 Dec 2020);
- Digital Compass communication<sup>3</sup> (COM(2021) 118 of 9 March 2021); and
- European Chips Act<sup>3</sup> Regulation (EU) 2023/1781<sup>4</sup> of the European Parliament and of the Council of 13 September 2023 establishing a framework of measures for strengthening Europe's semiconductor ecosystem and amending the DEP Regulation.

# 1.2 New approach for the work programme of the Chips JU

The Chips JU will contribute to the Chips for Europe Initiative. This requires a revision of the structure of the Work Programme to distinguish between the Chips for Europe Initiative (in 2023 and 2024 titled "Initiative") and the general Electronic Components and Systems (in 2023 and 2024 titled "non-Initiative") actions:

- the Electronic Components and Systems part of the programme that covers collaborative actions funded through HE, Cluster 4 and is the continuation of the

https://eur-lex.europa.eu/legal-content/EN/TXT/?uri=OJ%3AJOL 2023 229 R 0001

https://digital-strategy.ec.europa.eu/en/library/joint-declaration-processors-and-semiconductortechnologies

https://eur-lex.europa.eu/legal-content/en/TXT/?uri=CELEX%3A52021DC0118

- actions launched under the precedent Joint Undertakings. This part of the programme will fund bottom up and top-down calls, the top down calls are the so-called focus topics,
- the Chips for Europe Initiative part of the programme that covers capacity building actions: the pilot lines, the design platform, the competence centres, the quantum chips technology and activities around skills. This part of the programme covers both grants and procurements that are funded through HE and DEP.

# 1.3 Main objectives described in the SRIA.

The ECS SRIA 2024 (Chips GB 2023.56) identifies different major challenges that have emerged from the analysis of the foundational technologies, the cross-sectional technologies and the application key areas.

The challenges are frequently interdependent – they influence each other, become increasingly demanding, and impact on many areas, including technology innovation, industrial competitiveness, security, safety, business and environmental sustainability, society, etc. From this perspective, the major challenges represent key factors for the achievement of the four main common objectives, which are aligned with the European Commission Strategic Targets.

# 2. MULTIANNUAL WORK PROGRAMME

# 2.1 Actions implemented under the Chips for Europe initiative.

This section includes both:

- 1) capacity building activities for the operational objectives and
- 2) R&D&I activities.

that are described in the following appendices:

- Appendix 2 for the 2023 actions,
- Appendix 4 for the 2024 actions,
- Appendix 6 for the 2025 actions.<sup>5</sup>

The total multiannual budget for the activities, as annual commitments and per funding instrument, is:

Mio EURO	2023	2024	2025	2026	2027	TOTAL
Horizon Europe	339,659	406,510	302,831	-	-	1,049,000
Digital Europe	277,373	400,991	354,937	172,808	74,891	1,281,000

The following table summarizes the total indicative budget per action<sup>6</sup> or where possible the committed amounts:

Mio EURO	Indicative budget (Mio EURO)	Committed amounts (Mio EURO)
DEP Chips calls for 2023:		
DIGITAL-Chips-2023-SG-CPL-1	10	11,99
DIGITAL-Chips-2023-SG-CPL-2	10	7,85

Appendixes are available in separate documents.

<sup>6</sup> Maximum amounts are mentioned in Appendixes 2 and 4

DICITAL CI: 0000 CC CDI 0	10	14.12
DIGITAL-Chips-2023-SG-CPL-3	10	14,13
DIGITAL-Chips-2023-SG-CPL-4	10	4,56
TOTAL DEP SG Calls	40	38,53
DEP Chips calls for 2023:		
DIGITAL-Chips-2023-CfEoI-CPL-1	240	240,00
DIGITAL-Chips-2023-CfEoI-CPL-2	200	190,43
DIGITAL-Chips-2023-CfEoI-CPL-3	260	256,03
DIGITAL-Chips-2023-CfEoI-CPL-4	100	128,62
TOTAL DEP Procurements	800	815,08
HE Chips calls for 2023.		
HORIZON-Chips-2023-RIA-CPL-1	450	448,01
HORIZON-Chips-2023-RIA-CPL-2	210	216,81
HORIZON-Chips-2023-RIA-CPL-3	100	96,21
HORIZON-Chips-2023-RIA-CPL-4	70	46,51
TOTAL HE RIA Calls	830	807,54
DEP Chips calls for 2024:		
DIGITAL-Chips-2024-SG-CPL-5	10	5,18
DIGITAL-Chips-2024-SG-CCC-1	100	84,90
DIGITAL-Chips-2024-CSA-CCC-2	4	3,99
DIGITAL-Chips-2024-SG-CCC-3	16	
DIGITAL-Chips-2024-CSA-CDP-1	25	24,98
TOTAL DEP Calls	155	119,05
DEP Chips calls for 2024:		,
DIGITAL-Chips-2024-CfEoI-CPL-5	100	100,37
DIGITAL-Chips-2024-CfEoI-CDP-1	0	0
TOTAL DEP Procurements	100	100,37
HE Chips calls for 2024.		
HORIZON-Chips-2024-RIA-CPL-5	80	84,38
TOTAL HE RIA Calls	80	84,38
		,
DEP Chips calls for 2025:		
DIGITAL-JU-Chips-2025-SG-SSOI	30	
DIGITAL-JU-Chips-2025-CSA-DET	5	
TOTAL DEP Calls	35	
Procurements for 2025:		
Cloud Platform for the European	15	
Design Platform		
<b>TOTAL DEP Procurements</b>	15	
HE Chips calls for 2025.		
HORIZON-JU-Chips-2025-IA-EDA	20	
HORIZON-JU-Chips-2025-CSA	12	
HORIZON-Chips-2025-1-IA-LEAI	20	
HORIZON-JU-Chips-2025-FPA-QAC3	0	
HORIZON-JU-Chips-2025-SGA-QAC1	50	
HORIZON-JU-Chips-2025-SGA-QAC2	20	
HORIZON-JU-Chips-2025-RIA-SUP	220	
TOTAL HE Calls	342	
Lab to Fab (Funding instrument TBD)	50	

The EU budgets above will be matched by a commensurate amount of national contributions except for the budgets indicated with (\*) that will be 100% EU funded.

# 2.1.1 National Budgets for the Initiative Chips for Europe Initiative Calls 2025

Participating states	Chips- 2025- CSA- DET	Chips- 2025- IA - SUP	Chips- 2025- IA- EDA	Chips- 2025- CSA	Chips- 2025-1- IA-T2	Chips- 2025- SG- SSOI	Chips- 2026 - RIA- LFA	Chips- 2025- FPA- QAC3	Chips- 2025- SGA- QAC1	Chips- 2025- SGA- QAC2	Total (M€)
AT											
BE-FL											
BE-BR											
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# 2.2 Electronic Components and Systems actions

This section is dedicated to research and innovation activities not covered by the Chips for Europe initiative part. Those activities are financed with annual instalments under Horizon Europe. Actions are described in the following appendices:

- Appendix 1 for the 2023 actions,
- Appendix 3 for the 2024 actions,
- Appendix 5 for the 2025 actions. <sup>7</sup>

The total multiannual budget for the activities, as annual commitments and per funding instrument, is:

Mio EURO	2021	2022	2023	2024	2025	2026	2027	TOTAL Used	TOTAL ECS
Horizon Europe	178,19	165,40	236,97	216,00	231,00			1027,56	1306,22

The following table summarizes the total indicative budget per action<sup>8</sup> or where possible the committed amounts:

Mio EURO	Indicative budget (Mio EURO)	Committed amounts (Mio EURO)
HE Chips calls for 2025.		
HORIZON-JU-Chips-2025-IA	70	
HORIZON-JU-Chips-2025-IA FT1	80	
HORIZON-JU-Chips-2025-IA FT2	20	
HORIZON-JU-Chips-2025-IA-HIA	20	
HORIZON-JU-Chips-2025-RIA	40	
HORIZON-Chips-2025-CSA	1	
TOTAL HE Calls	231	

Appendixes are available in separate documents.

<sup>8</sup> Maximum amounts are mentioned in Appendixes 2 and 4

# 2.2.1 National Budgets for the European Components and Systems actions for 2025

AT BE-FL BE-BR BE-WL BG CY CZ DE DE TH DE SN DK EE EL ES AEI ES MAETD FI FR HR HU IE IL IS IT MIMIT IT MUR LT LV LU MT NL NO PL BG BG CY CY CZ DE	Participating states	Chips- 2025- IA	Chips- 2025- IA FT1	Chips 2025- IA FT2	Chips 2025- IA HIA	Chips 2025- RIA	Total (M€)
BE-BR         BE-WL           BG         G           CY         G           DE         G           DE TH         G           DE SN         G           DK         G           EE         G           EL         G           ES AEI         G           FI         G           FR         G           HR         G           HU         G           IE         G           II         G           IS         G           IT MIMIT         G           IT MUR         G           LT         G           LV         G           LU         G           MT         G           NO         G           PL         G	AT						
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# 3. SUPPORT TO OPERATIONS

## 3.1 Communication activities

The following summarises the key elements of the Communications' Policy and Strategy for the Chips JU<sup>9</sup>, secures an alignment between the multiannual and the annual plan and gives an indicative guide to the allocation of resources.

Internal Communications are to be regarded as part of the general management of the Office.

The concrete external communication objectives are to:

- 1. Increase the visibility and strengthen the credibility of the Chips JU as the leading European strategic initiative for focused, coordinated and competitive research and innovation activities that support the entire Electronic Components and Systems (ECS) value chain.
- **2. Demonstrate the added value of the Chips JU** programme in addressing societal and industrial challenges and needs, highlighting both technological advancements and economical contributions that align with EU priorities in digital transformation and sustainability.
- **3.** Build a strong sense of identity with the Chips JU programme among the stakeholders and strengthen the cohesion of the Chips JU community.
- **4. Increase the public and political awareness** of ECS technologies and their applications, recognising that ECS capability is a key enabler for securing global leadership and digital autonomy and enabling growth, job creation, and new economic opportunities across the EU.
- **5. Facilitate access to support mechanisms** at European, national and regional level that complement those offered by Chips JU, including additional financial resources, fostering greater stakeholder participation in funding opportunities.
- **6. Expand the outreach of the Chips JU** to new public and private audiences and potential partners with the objective of building bridges to other JUs, PPPs, clusters and national programmes.
- **7. Attract and secure political support** to maintain an adequate and effective European regulatory framework for ECS technologies.
- **8. Ensure** that the communication policies of all Chips JU members are aligned, and that the member activities reflect a consistent, unified message that reinforces Chips JU's objectives.
- **9.** Channel the information about the programme successes, breakthroughs and milestones to the general public, promoting tangible results of the Chips JU's funded projects.

<sup>&</sup>lt;sup>9</sup> An updated Communications' Policy and Strategy for the Chips JU will be submitted for a GB adoption.

- **10. Establish a dynamic calendar of actions/events** in alignment with the Chips JU stakeholders.
- **11. Promote the educational and skills development aspects** of the Chips JU's projects, raising awareness of training and learning opportunities that can foster the next generation of ECS talent across Europe.
- **12.** Establish clear metrics to measure communication impact, including audience reach, engagement, social media analysis, to ensure the communication strategy aligns with Chips JU's strategic goals and adapts based on performance data.

These objectives can be addressed by delivering easy-to-understand technical information about:

- ECS technologies,
- Chips JU programme,
- Funded projects and their added value induced by the public funding as well as their impact on competitiveness, growth and quality of daily life.

The following tables\* describe the potential audiences for external communication activities, the associated topics of interest and suggested media for communication.

	Potential audiences	Possible communication topics	Possible communication media
A. Peer groups and Chips JU (potential) stakeholders	<ul> <li>Active and potential participants in JU projects and initiatives;</li> <li>Industrial associations, European Commission and Participating States;</li> <li>Organisations with a specific interest in the activities and results of the JU programme</li> <li>RD&amp;I actors not (yet) participating in JU activities, specifically SMEs.</li> <li>Other funding instruments or organisations (e.g. EUREKA, other JUs, PPPs, etc.)</li> <li>National/regional organisations;</li> <li>Chips JU Mirror Groups (e.g. "Italy").</li> </ul>	<ul> <li>Themes to be addressed in future calls;</li> <li>Brokerage opportunities for active and potential project participants;</li> <li>How to create or engage in a project consortium; dos and don'ts when drafting a proposal;</li> <li>Creating support for the JU at relevant levels through dedicated events;</li> <li>Publication of results;</li> <li>Alignment of messages and coordinated actions between JU public and private stakeholders to underline the JU profile and strengthen important communication moments. Examples: joint press releases on call launches and funding decisions or sharing messages at national events.</li> </ul>	<ul> <li>Website;</li> <li>Social media (X, LinkedIn and YouTube channels);</li> <li>Publications;</li> <li>Workshops, seminars, forum sessions, brokerage events;</li> <li>Events at national level;</li> <li>Press releases;</li> <li>Public appearances of JU stakeholders.</li> </ul>

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	Potential audiences	Possible communication topics	Possible communication media
C. Interested public and specific audiences not related to Chips JU	<ul> <li>Sister JUs and other programmes focused on application areas covered by the JU;</li> <li>Civil society organisations.</li> <li>NGO's;</li> <li>Students;</li> <li>Other interested groups.</li> </ul>	<ul> <li>Key application areas: mobility, society, energy, health, security and the solutions that key digital technologies can offer;</li> <li>Interaction with relevant organisations on societal issues and possible technology solutions e.g. in the areas of health, automotive, energy, IoT, environment etc.;</li> <li>Opportunities for cooperation and for joint initiatives.</li> <li>Key application areas: mobility, society, energy, health, security and the solutions that key digital technologies can offer;</li> </ul>	<ul> <li>Website;</li> <li>Social media (X, LinkedIn and YouTube channels);</li> <li>Daily newspapers; technical Press, "Brussels-EC-press";</li> <li>Television, notably programmes that address science and technology for a broader audience;</li> <li>Dedicated information packages e.g. for schools.</li> </ul>

<sup>\*</sup> The reference descriptions in the above table might be updated to reflect further outcomes of any Governance Bodies recommendation on communication. However, it is expected that the major audiences identified will remain unchanged.

In 2025 the following activities are proposed:

# **3.1.1 Chips JU Events 2025**

- A. Major Chips JU branded events for communication: high-visibility events will serve as key platforms to communicate Chips JU's strategic initiatives, achievement and goals.
  - 1. **Chips JU Call Information Day:** this event will provide guidance on participation in the 2025 JU Calls and all related application aspects. This may be combined with a special information session for coordinators of running or new JU projects (see "Coordinators' Day" below).
  - 2. **Brokerage Event speaking slot:** Speaking slot at the consortium-building event organised by the JU Private Members (Industry Associations), to share general JU activities updates, and specific information about upcoming calls.
  - 3. **Chips JU advisory Stakeholder Forum:** This mandatory event (ex-Art. 140 of the SBA) of the Private Members Board (PMB), is open to all public and private stakeholders interested in key digital technologies. Its purpose is to inform stakeholders and collect feedback on the draft Strategic Research and Innovation Agenda. The JU Office provides support, if requested, along with the 3 Industry Associations, the European Commission, and potentially other stakeholders.
  - 4. **Chips JU Annual event:** As a flagship event, this annual event will strengthen identification with the Chips JU programme, highlight key achievements, increase visibility, and foster public engagement. Featuring result presentations, strategic discussions, and insights on future directions in ECS, it will bring together policy makers, industry leaders, and researchers.

### **B.** Chips JU events on specific topics;

- 1. Coordinator's Day: Dedicated to updates, training and guidance for project coordinators on best practices and managing of their projects (including their communication activities obligation).
- 2. **Chips JU Info Days**: workshops, seminars, or similar events, are to be foreseen. To that end, the JU may offer, as a service with specified budget, the (co-)organisation of such events, that should extend beyond the boundaries of a specific project, thereby ensuring fair treatment.
- 3. **PAB/NFA events:** tutorials, workshops, and other events to explain administrative processes and procedures.

# C. Specific events for communication with EU Institutions (Parliament, Council, EC) and national States representatives

**1. Breakfast Sessions** with MEPs / PermRep /DGs of the EC (in addition to DG CNECT).

- **2. Exhibition and promotion events at EU institutions:** active participation in events at EU institutions, potentially in collaboration with other JUs with shared interests.
- **3. National Representation events:** Events bringing together JU PAB/GB representatives as well as National delegates from the Permanent Representations of the countries participating in the JU.
- **4. Focused meetings with political representatives:** high-level meetings and focused discussion with relevant political representatives in selected national states capitals.
- **D.** Participating in key industrial fairs (such as Hannover Messe, München Messe, or Innovation Days, etc.). By participating in high-profile industrial fairs, Chips JU may strengthen its central player in the EU for electronics. In particular, the Chips JU may:

# 1. Enhance visibility and awareness of the programme

- Showcasing Chips JU contributions to innovation, technology development in the European semiconductor ecosystem.
- Establishing Chips JU as a leader and thought partner in the electronics and semiconductor space, enhancing its reputation among stakeholders.
- Exploring potential collaborations with other companies and startups.

# 2. Promote European Innovation

- Highlighting cutting-edge RD&I projects and breakthroughs funded and supported by the programme.
- Building trust by demonstrating the impact of the JU, as public-private partnerships, in advancing Europe's electronics sector.

## 3. Support the European Ecosystem

- Increasing stakeholder confidence and encouraging SMEs and startups in the European electronics sector to engage with Chips JU initiatives.
- Attracting Private Sector Interest: Showcases how Chips JU projects offer value to private investors and industry players.

# Support to Community-building and road-mapping facilitation.

- **1.** Support of other events organised by 3As (or Members of an Industry Association), if requested.
- **2.** Support by direct participation in relevant events organised by the European Commission.
- **3.** Support by direct participation in relevant events set up by National and/or Regional authorities to promote JU participation in their area. (Chips JU may pro-actively request such meetings ad-hoc, with specific National/Regional or other relevant authorities).

## **3.1.2 Publications**

## **Media Agencies Services**

To increase public and political awareness of Electronic Components and Systems (ECS) technologies and their applications, and to build broad support across European society, specialised assistance is essential for effective communication. To this end, Chips JU may partner with media agencies to execute various communication and event initiatives, using creative tools and solutions to maximize reach and impact (e.g., articles, campaigns, and promotional content).

## Flyers/Brochures:

Chips JU will publish informative brochures and flyers on relevant topics to promote the programme. Specific materials tailored to participants and different audiences will be developed, primarily designed for digital distribution but also available in eco-friendly print formats if necessary. Additionally, other eco-friendly promotional materials ("Merchandising") will be produced, as supporting tools for various events.

Chips JU will also support the funded projects, if requested. This support will include providing essential materials such as exhibition poster and project summaries, all professionally edited and produced. This support will ensure clear and effective communication to a wide audience.

## **Book of Projects**

Chips JU will publish its bi-annual "Book of Projects," an in-depth, visually engaging publication showcasing funded projects, highlighting key achievements and anticipated outcomes. This comprehensive guide will cover project summaries, objectives, and partner organisations, providing a clear picture of Chips JU's project portfolio. Distributed digitally, with print versions available for key events and stakeholders, the Book of Projects will serve as a valuable resource to track progress across the ECS landscape.

# **Monthly Newsletter**

A monthly Chips JU newsletter, titled "Chips Pulse" will be distributed to stakeholders and subscribers, providing regular updates on program developments, upcoming calls, event announcements, and project highlights. Each issue will feature:

- **Spotlights on funded projects**: Brief updates on milestones or achievements.
- **Upcoming events and calls**: Information on important dates and participation guidance.
- **Policy and industry news**: Insights on relevant ECS trends, regulatory changes, and strategic directions.
- **Stakeholder engagement opportunities**: Invitations to workshops, seminars, and other events where stakeholders can network and engage.

This newsletter will be a key tool for fostering regular engagement with Chips JU's community, providing timely insights, and ensuring transparency across activities.

#### Website and social media:

Chips JU will regularly share relevant information on its public website and social media channels, ranging from events, latest news, project updates, to the launch of calls for proposals.

The website contains attractive features that facilitate the dissemination of such information.

Special emphasis will be placed on social media platforms, (YouTube, X and LinkedIn), to launch advertisement campaigns on key topics such as JU structure, funded projects, scheduled events, and more.

#### Press releases.

In addition to press releases independently published by its members, Chips JU will issue its own press releases through its distribution channels. These will cover, but not limited to, the following key events:

- Chips JU Call launches.
- Outcomes of initiatives of the JU Members and their constituencies.
- Key decisions of European Institutions.
- Outcome of the Chips JU Calls (funding decisions previous year).

## **Promotional Video and Advertising Campaign**

To create a strong brand recognition, raise awareness and interest in the Chips JU programme, as well as to communicate key messages to target audiences, promotional videos and advertising campaigns might be foreseen.

# 3.2 Procurement and contracts

Procurement and contracts are managed in accordance with the provisions of the Financial Rules adopted by the Governing Board (Decision GB 2021.02 Annex 12).

To reach its objectives and adequately support its operations and infrastructures, the JU allocates funds to procure the necessary services and supplies.

To make tender and contract management as effective and cost-efficient as possible, the JU concludes Service Level Agreements (SLAs) with relevant Commission Services as well as its private members and makes use of inter-institutional framework contracts (FWC).

Also, the Office has started implementing **Back Office Arrangements** with other Joint Undertakings from end of 2022. The first arrangement concerns the accounting function that has ceased to be provided by DG Budget. The official Accounting Officer of the EU-Rail JU is appointed as the Accounting Officer for the CHIPS JU as from 1st December 2022.

Arrangements in the fields of Human Resources, Procurement and ICT services are in preparation, service level agreements are/will be signed to this effect with other Joint Undertakings.

In 2025, Chips JU foresees to run several procurement procedures for administrative and/or communication purposes mainly for very low and low value contracts. Procurements in the context of operational activities (operational procurement), in particular Pilot Line calls and Design Platform, are also foreseen. In the case of the Pilot Lines, the procurement of the pieces of equipment will be executed as Joint Procurement procedures. The Design Platform will be procured solely by the Chips JU.

# 3.3 IT and logistics

At present, eight Joint Undertakings are sharing the housing location in the building "White Atrium", Brussels Belgium.

The arrangements for the facilities are subject to a common contract for both the office space and the IT management of equipment, maintenance and help desk.

The eight Joint Undertakings are participating in the Common Back Office, the SLA for IT between the JUs (in the frame of the BOA) in which common tasks such as IT security policy, Business Continuity and Disaster Recovery Plans (BCP+DRP) have been allocated.

The Chips IT will be focusing on, the following roadmap:

## **3.3.1.** Cybersecurity Enhancements

Objective: Strengthen the cybersecurity posture of the organization.

Although under the jurisdiction of the Cyber BOA, the strategic importance of cybersecurity necessitates targeted focus. Furthermore, there are limitations to the expectations, due to our more complex and advanced environment. The following actions are planned:

Implement Advanced Threat Detection Tools: Deploy AI-driven threat detection systems to identify and mitigate potential risks in real-time.

Zero-Trust Architecture Adoption: Gradually transition to a zero-trust security framework to limit access to sensitive systems.

Employee Training & Awareness Campaigns: Conduct ongoing cybersecurity training programs and simulated phishing exercises for staff.

Regular Security Audits: Schedule biannual penetration testing and risk assessments.

Incident Response Plan Enhancement: Update and drill an organization-wide incident response plan to align with emerging threats.

Secure Guest Access: Implement strict access controls and monitoring for guest users to ensure their access is limited and secure.

Secure Board Portal and IKOP Reporting Tool: Enhance security measures for the board portal and IKOP reporting tool to protect sensitive information, including multi-factor authentication, encryption, and regular security audits.

# 3.3.2. Digital Transformation Initiatives

Objective: Drive innovation and digital transformation, utilizing the available tools to propel the organization forward.

To maintain technological leadership, the program will focus on:

AI and Automation Integration: Identify and automate routine processes to improve efficiency and reduce costs.

Cloud Optimization: Expand and optimize the use of cloud infrastructure for scalability and operational resilience.

User-Centric Digital Platforms: Design and launch platforms that provide intuitive user experiences for internal and external stakeholders, including improvements to IKOP data entry to streamline processes and enhance data accuracy.

Data Analytics & Insights: Implement advanced analytics to leverage organizational data for better decision-making.

Collaborative Tools Deployment: Enhance the productivity of teams by deploying or upgrading collaborative tools like shared workspaces and communication platforms.

Co-pilot Implementation: Introduce AI-based co-pilot systems to assist employees with documentation, and other repetitive tasks, increasing overall productivity.

## 3.3.3 IT Governance and Compliance

Objective: Ensure adherence to regulatory standards and IT governance, focusing on the needs of Chips JU and advanced technologies. Considering the new DPIA, we need to have an overview of how we work, including areas such as data retention.

Key initiatives include:

Regulatory Alignment: Conduct a thorough review and update policies to comply with Chips JU and relevant regulatory frameworks.

Technology Risk Management: Enhance frameworks for identifying and mitigating technology-related risks associated with advanced tech adoption.

Audit and Monitoring Systems: Deploy real-time monitoring tools to ensure compliance with governance protocols.

Stakeholder Engagement: Regularly engage with Chips JU representatives to align IT strategies with their priorities and expectations.

# 3.4 JU Executive Team – HR matters

The number of staff employed by Chips JU in 2025 will reach 50 statutory staff.

Recruitment procedures for 2025 positions have already started last quarter of 2024, namely 6 new posts are intended to be recruited. Moreover, 2 Seconded National Experts are also expected to be recruited in 2025.

# 3.5 Administrative Budget and Finance

The administrative budget of Chips JU will be **10,918,640.00** € for 2025.

Funding sources for the budget of Chips JU are at present:

- The EU budget for the operational costs and 70% of the running costs,
- The Private Members for the remaining 30% of the running costs.

The part of the running costs on the total budget is kept at a very low level which is to be considered as an indicator for efficiency. More specifically, the part of **administrative costs** in the total budget will be as follows:

- with regard to Commitment Appropriations: 1.19%
- with regard to Payment Appropriations: 1.17%

# 3.6 Data protection and conflicts of interest

## **Data protection**

The EUI-GDPR N°2018/1725, implemented by Chips JU in internal set of documents, is regularly updated to include recent developments. Mostly, these are internal privacy policies that are concerned, as published on the CHIPS JU website.

The role of the Data Protection Officer (DPO) is exercised by the Legal Officer of CHIPS JU, assisted by an assistant legal officer.

### **Conflicts of interest**

The Governing Board has adopted comprehensive rules on the prevention and management of conflicts of interest (KDT GB 2021.02 Annex 4). It addresses all actors involved in the Joint Undertaking activities, including staff, PAB and GB members, experts involved in projects reviews and evaluations, participants in procurement and recruitment committees. Antifraud awareness t and Ethics training are expected to be mandatory for all staff as of 2025. Both trainings are orientated to address potential conflict of interest and best practices.

# 4. GOVERNANCE

Governance of the Joint Undertaking includes the following bodies:

The Governing Board has overall responsibility for the strategic orientation and the
operations of the Chips Joint Undertaking and supervises the implementation of its
activities.

The Chair of the Governing Board is Mr Stefan Finkbeiner.

- The **Executive Director** is the chief executive responsible for the day-to-day management of the Chips Joint Undertaking in accordance with the decisions of the Governing Board. Since 16<sup>th</sup> October 2023, Prof. **Jari Kinaret** is the Executive Director.
- The **Public Authorities Board** is competent for matters related to calls for proposals and allocation of public funding.

The Chair is Mr Francis Deprez.

• The **Private Members Board** is responsible for drawing up the SRIA.

The Chair is Mr Jean-Luc di Paola-Galloni.

# INTERNAL CONTROL FRAMEWORK

#### 5.1 **Financial procedures**

## **Legacy projects (ECSEL)**

The financial procedure for projects under H2020 depends on the H2020 IT tools developed by the European Commission (Compass, Sygma). These IT tools encompass the full cycle of the process, including work-flows, check-lists, etc.

# Chips projects

The financial procedure for grants under Horizon Europe and Digital Europe Programme depends on the IT tools developed by the European Commission (Compass, Sygma). These IT tools encompass the full cycle of the process, including work-flows, check-lists, etc.

Procurements under Digital Europe Programme shall be managed in accordance with Regulation (EU) 2021/694 of the European Parliament and of the Council and Regulation (EU) 2023/1781 of the European Parliament and of the Council.

#### 5.2 **Ex-ante and ex-post controls.**

The internal control processes and methods have been subject, from the first days of existence of CHIPS JU, to a decision of the Governing Board (KDT GB 2021.02 Annex 11) adopting the Internal Control Framework of the JU.

With regard to financial matters, ex-ante and ex-post controls are organised in accordance with the Financial Rules of the CHIPS JU (KDT GB 2021.02 Annex 12, in particular Articles 21 and 22).

#### 5.3 **Audits**

Audits are organised both on an internal and external basis:

Internal audits are operated by the internal auditor of the JU (the Internal Audit Service of the European Commission) and may be operated by the staff member appointed by the Governing Board for performing the internal audit capability, in accordance with the provisions of Chapter 5 of the Financial Rules of the Chips JU.<sup>10</sup>

External audits are operated by an independent external auditor and by the European Court of Auditors in accordance with the provisions of Chapter 9 of the Financial Rules of the

<sup>10</sup> Decision KDT GB 2021.02 Annex 12

Chips JU. The European Court of Auditors reports to the European Parliament and the Council, responsible for the discharge procedure.

**Ex-post audits of beneficiaries** are also operated on behalf of the CHIPS JU, with methods which are adapted to the specificities of the programmes:

## **Legacy projects (ECSEL)**

Under the regime of H2020, the JU has defined the needs and methods for the ex-post audits, in close cooperation with the CIC of the European Commission, in view of a coordinated approach of audits of beneficiaries. A common audit plan for all EU services involved in the H2020 programme is implemented by the CIC, acting on behalf of the CHIPS JU.

## Chips projects

Under the regime of Horizon Europe, the CIC of the European Commission has defined the needs and methods for the ex-post audits in cooperation with EU granting authorities in view of a coordinated approach of audits of beneficiaries, as implemented under H2020. A common audit plan for all EU services involved in the Horizon Europe is implemented by the CIC, acting on behalf of the CHIPS JU.

Under the regime of Digital Europe Programme, DG CNECT of the European Commission and the executive agency HADEA have established the needs and methods for the ex-post audits in cooperation with EU granting authorities in view of a coordinated approach of audits of beneficiaries. A common audit plan for all EU services involved in Digital Europe Programme is implemented by HADEA, acting on behalf of the CHIPS JU.

# 6. APPENDICES DESCRIBING THE ACTIVITIES

Appendix 1 2023 non-initiative

Appendix 2 2023 initiative

Appendix 3 2024 non-initiative

Appendix 4 2024 initiative

Appendix 5 2025 Electronic Components and Systems

Appendix 6 2025 Chips for Europe Initiative

All Appendices are separate documents.

# 7. GENERAL ANNEXES

The General Annexes to the Multiannual Work Programme are provided in a separate document.